Board Characteristics - 4 LAYER BOARD

1. Tg > 170°C
2. Minimum trace width: 0.005" and clearance: 0.005"
3. 1 oz copper for all layers
4. Electroless Nickel Immersion Gold plating, with min. Ni: 2.5-5 μm; Au: 0.05-0.2 μm.
5. Board Thickness: 0.062
6. FMS tolerances: ±0.003 unless specified otherwise.
7. Zc=50 Ohm, Zd=100 Ohm Controlled Impedance on 5-mil traces
8. Apply Solder Mask over bare copper.
9. Do not increase size of thermal pads and associated spoke connections on holes.
10. Remove all non-functional inner layer pads for pins and vias.

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### BOARD's DRILL SCHEDULE

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<th>DRILL SYMBOL</th>
<th>DRILL SIZE</th>
<th>COUNT</th>
<th>PLATED</th>
<th>TOLERANCE</th>
<th>COMMENT</th>
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3.4 Power

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University of Chicago
Electronics Development Group
DAMIC - CBB
Specification Drawing
2992-B A
1/2
M. Bogdan
M. Bogdan